

Field Device Integration (FDI®) - Part 7:
Communication Devices



EESTI STANDARDI EESSÕNA

NATIONAL FOREWORD

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English Version

Field Device Integration (FDI®) - Part 7: Communication Devices
(IEC 62769-7:2023)

Intégration des appareils de terrain (FDI®) - Partie 7:
Appareils de Communication
(IEC 62769-7:2023)

Feldgeräteintegration (FDI®) - Teil 7: FDI-
Kommunikationsgeräte
(IEC 62769-7:2023)

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European foreword

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**Field Device Integration (FDI®) –
Part 7: Communication Devices**

**Intégration des appareils de terrain (FDI®) –
Partie 7: Appareils de Communication**



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IEC Secretariat
3, rue de Varembe
CH-1211 Geneva 20
Switzerland

Tel.: +41 22 919 02 11
info@iec.ch
www.iec.ch

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INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Field Device Integration (FDI®) –
Part 7: Communication Devices**

**Intégration des appareils de terrain (FDI®) –
Partie 7: Appareils de Communication**

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CONTENTS

FOREWORD.....	6
1 Scope.....	8
2 Normative references	9
3 Terms, definitions, abbreviated terms, acronyms and conventions	9
3.1 Terms and definitions.....	9
3.2 Abbreviated terms and acronyms	9
3.3 Conventions.....	10
3.3.1 EDDL syntax.....	10
3.3.2 Capitalizations	10
3.3.3 Graphical notation	10
4 Overview	10
5 FDI® Communication Package	12
5.1 General.....	12
5.2 EDD.....	12
5.2.1 General rules.....	12
5.2.2 Device component	13
5.2.3 CommunicationDevice component	14
5.2.4 Communication service provider component	15
5.2.5 Connection Point component	17
5.2.6 Connection Point collection.....	17
5.2.7 Network component.....	18
5.2.8 ValidateNetwork	19
5.2.9 ValidateModules	20
5.2.10 UIP specifics	20
5.2.11 Deployment	21
6 Communication relations	21
7 FDI® Communication Server definition	22
7.1 General.....	22
7.2 General characteristics	22
7.3 Information Model	22
7.3.1 General	22
7.3.2 CommunicationServerType.....	25
7.3.3 ServerCommunicationDeviceType	29
7.3.4 ServerCommunicationServiceType	33
7.4 OPC UA Server Profile for FDI® Communication Server	37
7.5 Mapping the FDI® Server Information Model to the FDI® Communication Server IM	38
7.5.1 General	38
7.5.2 Information Model differences.....	38
7.6 Installer.....	39
7.7 FDI® Communication Package	39
7.7.1 General	39
7.7.2 EDD for lightweight Communication Server.....	40
7.7.3 EDD for multi-channel Communication Server	40
7.7.4 COMMANDs in EDDs for FDI® Communication Servers	40
7.7.5 Documentation	41

7.8	Handling and behaviour	41
7.8.1	General	41
7.8.2	Deployment	42
7.8.3	Server configuration	42
7.8.4	Start up	43
7.8.5	Shutdown	43
7.8.6	Watchdog	43
7.8.7	Establish the OPC UA connection	43
7.8.8	Instantiate the Communication Server	44
7.8.9	Configure the communication hardware	44
7.8.10	Configure the Network	44
7.8.11	Parameterize	44
7.8.12	Initialize	44
7.8.13	Create the communication service object	44
7.8.14	Communication relation	45
7.8.15	Connect	45
7.8.16	Disconnect	45
7.8.17	Abort indication	46
7.8.18	Scan	46
7.8.19	SetAddress	46
8	FDI® Communication Gateway definition	46
8.1	General	46
8.2	Information Model	46
8.2.1	General	46
8.2.2	CommunicationGatewayType	47
8.2.3	GatewayCommunicationDeviceType	48
8.2.4	GatewayCommunicationServiceType	51
8.3	FDI® Communication Package	55
8.3.1	General	55
8.3.2	EDD	56
8.4	Handling and behaviour	57
8.4.1	General	57
8.4.2	Deployment	58
8.4.3	Start up	58
8.4.4	Configure the communication hardware	58
8.4.5	Configure the Network	58
8.4.6	Parameterize	58
8.4.7	Communication relation	59
8.4.8	Connect	59
8.4.9	Disconnect	59
8.4.10	Abort indication	59
8.4.11	Scan	59
8.4.12	Communication Error Handling	60
Annex A (informative)	Layered protocols	61
A.1	General	61
A.2	Convention for protocol specific annex creation	61
A.2.1	General	61
A.2.2	Connection Point	61
A.3	FDI® Communication Package definition	63

A.3.1	Communication services	63
A.3.2	Connection Point	63
A.3.3	Network	63
A.4	Representation in the Information Model	63
Annex B (normative)	Namespace and Mappings	64
Figure 1	FDI® architecture diagram	8
Figure 2	FDI® communication infrastructure architecture	11
Figure 3	Communication relation	21
Figure 4	Communication relation state chart	22
Figure 5	FDI® Communication Server AddressSpace	24
Figure 6	CommunicationServerType	25
Figure 7	ServerCommunicationDeviceType	29
Figure 8	ServerCommunicationServiceType	34
Figure 9	Information Model differences (example)	38
Figure 10	FDI® Communication Server state machine	42
Figure 11	Communication relation state chart	45
Figure 12	Gateway information model	47
Figure 13	CommunicationGatewayType	48
Figure 14	GatewayCommunicationDeviceType	49
Figure 15	GatewayCommunicationServiceType	52
Figure 16	Nested Communication	58
Table 1	ValidateNetwork Action arguments	20
Table 2	ValidateModules Action arguments	20
Table 3	CommunicationServerType definition	25
Table 4	MethodSet of CommunicationServerType	25
Table 5	Reset Method arguments	26
Table 6	Reset Method AddressSpace definition	26
Table 7	Initialize Method arguments	27
Table 8	Initialize Method AddressSpace definition	27
Table 9	AddComponent Method arguments	28
Table 10	AddComponent Method AddressSpace definition	28
Table 11	RemoveComponent Method arguments	29
Table 12	RemoveComponent Method AddressSpace definition	29
Table 13	ServerCommunicationDeviceType definition	30
Table 14	MethodSet of ServerCommunicationDeviceType	30
Table 15	Scan Method arguments	31
Table 16	Scan Method AddressSpace definition	31
Table 17	Scan Method arguments	32
Table 18	Scan Method AddressSpace definition	32
Table 19	ResetScan Method arguments	32
Table 20	ResetScan Method AddressSpace definition	33
Table 21	SetAddress Method arguments	33

Table 22 – ServerCommunicationServiceType definition	34
Table 23 – MethodSet of ServerCommunicationServiceType	34
Table 24 – Connect Method arguments	35
Table 25 – Disconnect Method arguments	36
Table 26 – Transfer Method arguments	36
Table 27 – GetPublishedData Method arguments	37
Table 28 – FDI®CommunicationServer_Facet definition	37
Table 29 – CommunicationGatewayType definition	48
Table 30 – GatewayCommunicationDeviceType definition	49
Table 31 – MethodSet of GatewayCommunicationDeviceType	49
Table 32 – Scan Method arguments	50
Table 33 – Scan Method AddressSpace definition	50
Table 34 – ScanNext Method arguments	51
Table 35 – ScanNext Method AddressSpace definition	51
Table 36 – GatewayCommunicationServiceType definition	52
Table 37 – MethodSet of GatewayCommunicationServiceType	53
Table 38 – Connect Method arguments	54
Table 39 – Transfer Method arguments	55

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FIELD DEVICE INTEGRATION (FDI®) –**Part 7: Communication Devices****FOREWORD**

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IEC 62769-7 has been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation. It is an International Standard.

This third edition cancels and replaces the second edition published in 2021. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) added ScanExtended Method.

The text of this International Standard is based on the following documents:

Draft	Report on voting
65E/859/CDV	65E/916/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/publications.

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FIELD DEVICE INTEGRATION (FDI®) –

Part 7: Communication Devices

1 Scope

This part of IEC 62769 specifies the elements implementing communication capabilities called Communication Devices.

The overall FDI®¹ architecture is illustrated in Figure 1. The architectural components that are within the scope of this document have been highlighted in this illustration. The document scope with respect to FDI® Packages is limited to Communication Devices. The Communication Server shown in Figure 1 is an example of a specific Communication Device.

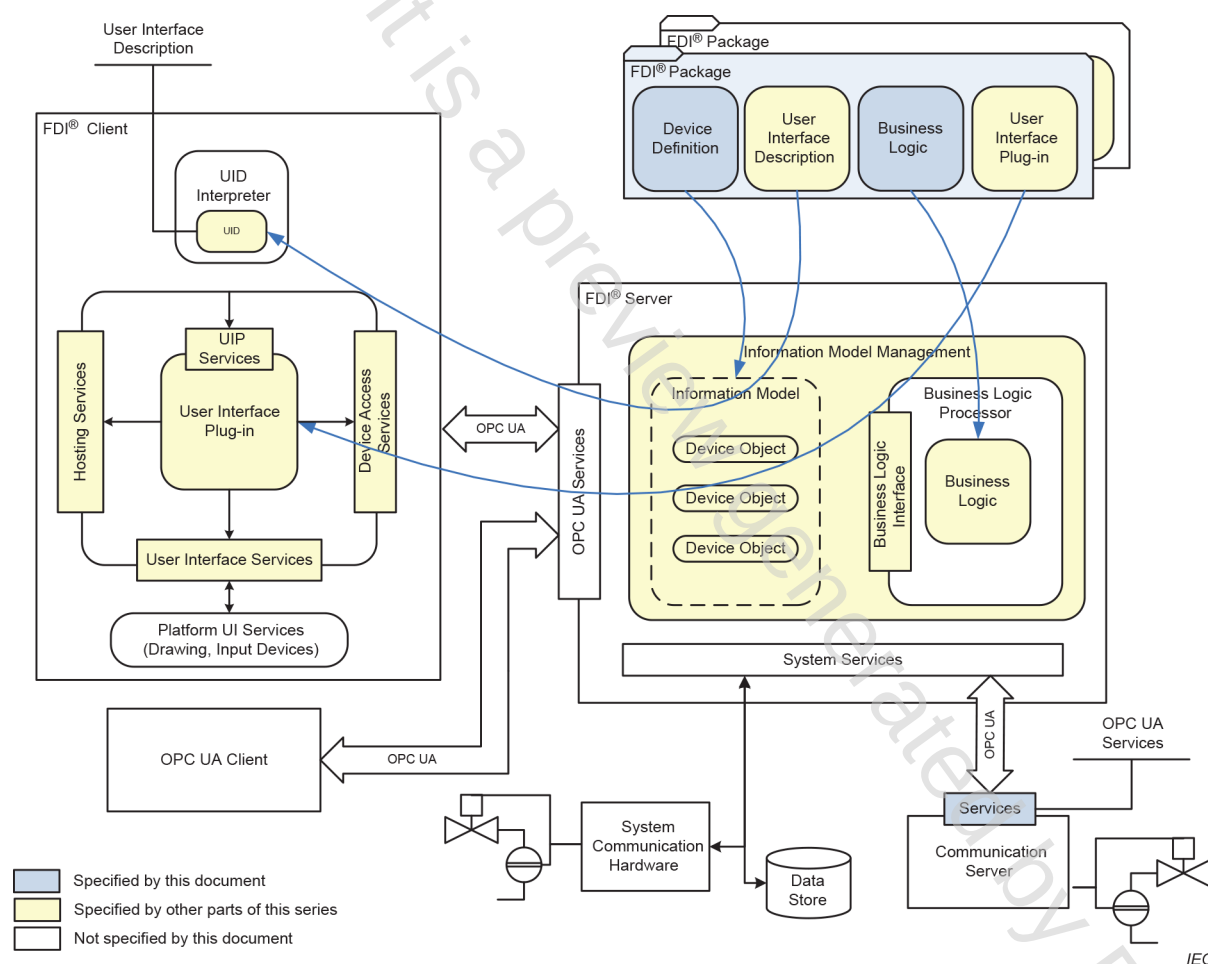


Figure 1 – FDI® architecture diagram

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IEC 61804-3, *Devices and integration in enterprise systems – Function blocks (FB) for process control and electronic device description language (EDDL) – Part 3: EDDL syntax and semantics*

IEC 61804-4, *Devices and integration in enterprise systems – Function blocks (FB) for process control and electronic device description language (EDDL) – Part 4: EDD interpretation*

IEC TR 62541-1, *OPC Unified Architecture – Part 1: Overview and concepts*

IEC 62541-4, *OPC Unified Architecture – Part 4: Services*

IEC 62541-6, *OPC Unified Architecture – Part 6: Mappings*

IEC 62541-7, *OPC unified architecture – Part 7: Profiles*

IEC 62541-100, *OPC Unified Architecture – Part 100: Device Interface*

IEC 62769-1, *Field Device Integration (FDI®) – Part 1: Overview*

IEC 62769-2, *Field Device Integration (FDI®) – Part 2: Client*

IEC 62769-3, *Field Device Integration (FDI®) – Part 3: Server*

IEC 62769-4:2023, *Field Device Integration (FDI®) – Part 4: FDI® Packages*

IEC 62769-5, *Field Device Integration (FDI®) – Part 5: FDI® Information Model*

3 Terms, definitions, abbreviated terms, acronyms and conventions

3.1 Terms and definitions

For the purposes of this document, the terms and definitions given in IEC 62769-1, IEC 62769-3, IEC 62541-6 and the following apply.

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- IEC Electropedia: available at <https://www.electropedia.org/>
- ISO Online browsing platform: available at <https://www.iso.org/obp>

3.1.1

Gateway

Communication Device that enables to bridge between different physical networks or different protocols

3.2 Abbreviated terms and acronyms

For the purposes of this document, the abbreviated terms and acronyms given in IEC 62769-1, IEC 62541-6 and the following apply.